

PALM INTRANET

Day : Monday
Date: 2/9/2004
Time: 07:00:29

Inventor Name Search Result

Your Search was:

Last Name = HIGASHI

First Name = MITSUTOSHI

Application#	Patent#	Status	Date Filed	Title	Inventor Name 40
<u>10704156</u>	Not Issued	019	11/10/2003	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	HIGASHI, MITSUTOSHI
<u>10645478</u>	Not Issued	018	01/01/0001	CAPACITOR, CIRCUIT BOARD, METHOD OF FORMATION OF CAPACITOR, AND METHOD OF PRODUCTION OF CIRCUIT BOARD	HIGASHI, MITSUTOSHI
<u>10453311</u>	Not Issued	041	06/03/2003	SUBSTRATE-EMBEDDED CAPACITOR, PRODUCTION METHOD THEREOF, AND CIRCUIT BOARD	HIGASHI, MITSUTOSHI
<u>10430652</u>	Not Issued	041	05/06/2003	TERMINAL, SEMICONDUCTOR DEVICE, TERMINAL FORMING METHOD AND FLIP CHIP SEMICONDUCTOR DEVICE MANUFACTURING METHOD	HIGASHI, MITSUTOSHI
<u>10335689</u>	Not Issued	030	01/02/2003	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	HIGASHI, MITSUTOSHI
<u>10270823</u>	Not Issued	030	10/15/2002	SEMICONDUCTOR DEVICE AND METHOD OF PRODUCTION OF SAME	HIGASHI, MITSUTOSHI
<u>10162598</u>	Not Issued	095	06/06/2002	SEMICONDUCTOR DEVICE AND METHOD OF PRODUCTION OF SAME	HIGASHI, MITSUTOSHI
<u>10162587</u>	Not Issued	095	06/06/2002	SEMICONDUCTOR DEVICE AND METHOD OF PRODUCTION OF SAME	HIGASHI, MITSUTOSHI
<u>10114518</u>	Not	030	04/02/2002	SEMICONDUCTOR ELEMENT,	HIGASHI,

	Issued			CONNECTION STRUCTURE THEREOF, SEMICONDUCTOR DEVICE USING A PLURALITY OF SUCH ELEMENTS AND PROCESSES FOR MAKING THE SAME	mitsutoshi
<u>10083788</u>	<u>6678144</u>	150	02/27/2002	CAPACITOR, CIRCUIT BOARD WITH BUILT-IN CAPACITOR AND METHOD FOR PRODUCING THE SAME	HIGASHI, MITSUTOSHI
<u>10043943</u>	Not Issued	161	01/11/2002	HEAT RADIATION FIN USING A CARBON FIBER REINFORCED RESIN AS HEAT RADIATION PLATES STANDING ON A SUBSTRATE	HIGASHI, MITSUTOSHI
<u>10013398</u>	<u>6548326</u>	150	12/13/2001	SEMICONDUCTOR DEVICE AND PROCESS OF PRODUCING SAME	HIGASHI, MITSUTOSHI
<u>09973111</u>	<u>6538332</u>	150	10/09/2001	SEMICONDUCTOR DEVICE AND METHOD OF PRODUCTION OF SAME	HIGASHI, MITSUTOSHI
<u>09881004</u>	<u>6522719</u>	150	06/14/2001	METHOD AND APPARATUS FOR MEASURING A BUMP ON A SUBSTRATE	HIGASHI, MITSUTOSHI
<u>09874277</u>	Not Issued	161	06/06/2001	SEMICONDUCTOR DEVICE HAVING EXTERNAL CONNECTING TERMINALS AND PROCESS FOR MANUFACTURING THE DEVICE	HIGASHI, MITSUTOSHI
<u>09847193</u>	<u>6583383</u>	150	05/02/2001	METHOD AND APPARATUS FOR CUTTING A SEMICONDUCTOR WAFER	HIGASHI, MITSUTOSHI
<u>09778119</u>	<u>6354480</u>	150	02/05/2001	APPARATUS FOR POSITIONING A THIN PLATE	HIGASHI, MITSUTOSHI
<u>09767432</u>	Not Issued	041	01/23/2001	HEAT RADIATION FIN USING A CARBON FIBER REINFORCED RESIN AS HEAT RADIATION PLATES STANDING ON A SUBSTRATE	HIGASHI, MITSUTOSHI
<u>09760396</u>	Not Issued	093	01/12/2001	SEMICONDUCTOR DEVICE HAVING A CARBON FIBER REINFORCED RESIN AS A HEAT RADIATION PLATE HAVING A CONCAVE	HIGASHI, MITSUTOSHI

				PORTION	
<u>09734863</u>	Not Issued	071	12/12/2000	BUMP INSPECTION APPARATUS AND METHOD	HIGASHI, MITSUTOSHI
<u>09734855</u>	Not Issued	161	12/11/2000	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	HIGASHI, MITSUTOSHI
<u>09669729</u>	<u>6544428</u>	150	09/26/2000	METHOD FOR PRODUCING A MULTI-LAYER CIRCUIT BOARD USING ANISOTROPIC ELECTRO-CONDUCTIVE ADHESIVE LAYER	HIGASHI, MITSUTOSHI
<u>09669728</u>	<u>6331679</u>	150	09/26/2000	MULTI-LAYER CIRCUIT BOARD USING ANISOTROPIC ELECTRO-CONDUCTIVE ADHESIVE LAYER	HIGASHI, MITSUTOSHI
<u>09645299</u>	Not Issued	093	08/24/2000	INSPECTION APPARATUS FOR SEMICONDUCTOR DEVICE AND PARTS MOUNTER USING SAME	HIGASHI, MITSUTOSHI
<u>09639262</u>	Not Issued	161	08/15/2000	SEMICONDUCTOR DEVICE AND PRODUCTION THEREOF	HIGASHI, MITSUTOSHI
<u>09627976</u>	<u>6404070</u>	150	07/28/2000	SEMICONDUCTOR DEVICE	HIGASHI, MITSUTOSHI
<u>09591785</u>	<u>6420787</u>	150	06/12/2000	SEMICONDUCTOR DEVICE AND PROCESS OF PRODUCING SAME	HIGASHI, MITSUTOSHI
<u>09430189</u>	Not Issued	041	10/29/1999	SEMICONDUCTOR DEVICE HAVING EXTERNAL CONNECTING TERMINALS AND PROCESS FOR MANUFACTURING THE DEVICE	HIGASHI, MITSUTOSHI
<u>09422850</u>	<u>6586845</u>	150	10/25/1999	SEMICONDUCTOR DEVICE MODULE HAVING HEAT SPREADER ENGAGING A MOUNTING BOARD	HIGASHI, MITSUTOSHI
<u>09333662</u>	<u>6312551</u>	150	06/16/1999	METHOD FOR MOUNTING SEMICONDUCTOR CHIP ONTO CIRCUIT BOARD	HIGASHI, MITSUTOSHI
<u>09333515</u>	<u>6281567</u>	150	06/15/1999	SUBSTRATE FOR MOUNTING SEMICONDUCTOR CHIP WITH PARALLEL CONDUCTIVE LINES	HIGASHI, MITSUTOSHI
<u>09040370</u>	<u>5960308</u>	150	03/18/1998	PROCESS FOR MAKING A CHIP SIZED SEMICONDUCTOR DEVICE	HIGASHI, MITSUTOSHI

<u>08960336</u>	<u>5918746</u>	150	10/29/1997	CARRIER FRAME USED FOR CIRCUIT BOARDS	HIGASHI , MITSUTOSHI
<u>08930514</u>	<u>5902472</u>	150	09/30/1997	AQUEOUS SOLUTION FOR FORMING METALLIC COMPLEX TIN-SILVER ALLOY PLATING SOLUTION AND METHOD OF PLATING WITH SAID PLATING SOLUTION	HIGASHI , MITSUTOSHI
<u>08909594</u>	<u>6147311</u>	150	08/12/1997	MULTI-LAYER CIRCUIT BOARD USING ANISOTROPIC ELECTROCONDUCTIVE ADHESIVE LAYER AND METHOD FOR PRODUCING SAME	HIGASHI , MITSUTOSHI
<u>08895145</u>	<u>5918113</u>	150	07/16/1997	PROCESS FOR PRODUCING A SEMICONDUCTOR DEVICE USING ANISOTROPIC CONDUCTIVE ADHESIVE	HIGASHI , MITSUTOSHI
<u>08698624</u>	<u>5777386</u>	150	08/16/1996	SEMICONDUCTOR DEVICE AND MOUNT STRUCTURE THEREOF	HIGASHI , MITSUTOSHI
<u>08620290</u>	<u>5834844</u>	150	03/22/1996	SEMICONDUCTOR DEVICE HAVING AN ELEMENT WITH CIRCUIT PATTERN THEREON	HIGASHI , MITSUTOSHI
<u>08502811</u>	<u>5732465</u>	150	07/14/1995	METHOD OF MANUFACTURING ONE SIDE RESIN SEALING TYPE SEMICONDUCTOR DEVICES	HIGASHI , MITSUTOSHI
<u>08227354</u>	Not Issued	161	04/13/1994	SEMICONDUCTOR DEVICE HAVING MOUNTING TERMINALS	HIGASHI , MITSUTOSHI

Inventor Search Completed: No Records to Display.

Search Another: Inventor

Last Name	First Name	Search
HIGASHI	MITSUTOSHI	

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)